

CLAIMS:

1. A label for in-mold decorating, comprising:

- (I) a thermoplastic resin film base layer;
- (II) an interlayer overlying said base layer and comprising:
  - (a) a thermoplastic resin composition, and
  - (b) at least one antistatic agent; and
- (III) a heat-sealable resin layer overlying said interlayer.

2. The label according to claim 1, wherein said heat-sealable resin layer (III) comprises an embossed surface.

3. The label according to claim 1, wherein said antistatic agent comprises a polyamide copolymer.

4. The label according to claim 1, wherein said antistatic agent comprises a polyether ester amide.

5. The label according to claim 1, wherein said interlayer comprises:

- (a) 50 to 95% by weight of a thermoplastic resin as the thermoplastic resin composition;
- (b) 5 to 35% by weight of a polyether ester amide as the antistatic agent; and
- (c) 0 to 10% by weight of a polyamide resin as the antistatic agent.

6. The label according to claim 5, wherein the thermoplastic resin (a) is a polyolefin resin.

7. The label according to claim 5, wherein said thermoplastic resin composition further comprises (d) 0.01 to 5% by weight of a metal salt.

8. The label according to claim 5, wherein said thermoplastic resin composition further comprises (e) 0.5 to 20% by weight of an ionomer.

9. The label according to claim 7, wherein said thermoplastic resin composition further comprises (e) 0.5 to 20% by weight of an ionomer.

5           10. The label according to claim 5, wherein said thermoplastic resin composition further comprises (f) 1 to 20% by weight of modified low-molecular weight polyethylene.

11. The label according to claim 7, wherein said thermoplastic resin composition further comprises (f) 1 to 20% by weight of modified low-molecular weight polyethylene.

10           12. The label according to claim 8, wherein said thermoplastic resin composition further comprises (f) 1 to 20% by weight of modified low-molecular weight polyethylene.

13. The label according to claim 9, wherein said thermoplastic resin composition  
15 further comprises (f) 1 to 20% by weight of modified low-molecular weight polyethylene.

14. The label according to claim 1, wherein said thermoplastic resin composition comprises a polyolefin resin.

20           15. The label according to claim 1, wherein said thermoplastic resin composition comprises (d) 0.01 to 5% by weight of a metal salt.

16. The label according to claim 1, wherein said thermoplastic resin composition further comprises (e) 0.5 to 20% by weight of an ionomer.

25           17. The label according to claim 1, wherein said thermoplastic resin composition further comprises (f) 1 to 20% by weight of modified low-molecular weight polyethylene.

18. The label according to claim 1, wherein said heat-sealable resin layer (III)  
30 comprises a polyethylene resin having a crystallinity of 10 to 60%, a number average molecular weight of 10,000 to 40,000, and a melting point of 50 to 130°C.

19. The label according to claim 1, wherein said heat-sealable resin layer (III) comprises a polyethylene resin having a crystallinity of 10 to 60%.

5           20. The label according to claim 1, wherein said heat-sealable resin layer (III) comprises a polyethylene resin having a number average molecular weight of 10,000 to 40,000.

10           21. The label according to claim 1, wherein said heat-sealable resin layer (III) comprises a polyethylene resin having a melting point of 50 to 130°C.

22. The label according to claim 1, wherein said interlayer (II) has a thickness of 0.5 to 20 µm, and said heat-sealable resin layer (III) has a thickness of 0.5 to 20 µm.

15           23. The label according to claim 1, wherein said interlayer (II) has a thickness of 0.5 to 20 µm.

24. The label according to claim 1, wherein said heat-sealable resin layer (III) has a thickness of 0.5 to 20 µm.

20           25. The label according to claim 1, which has a surface resistivity of  $1 \times 10^9$  to  $1 \times 10^{14}$  Ω/square on a side of said heat-sealable resin layer (III) opposite to a side thereof facing said interlayer (II).

25           26. The label according to claim 1, further comprising at least one selected from the group consisting of an inorganic fine powder, an organic filler, and combinations thereof.

30           27. The label according to claim 1, wherein said base layer (I) further comprises at least one selected from the group consisting of an inorganic fine powder, an organic filler, and combinations thereof.

28. A labeled, resin molded article, comprising the label according to claim 1 integrally adhered thereto by thermal fusion bonding.

29. A labeled, resin molded article, comprising the label according to claim 1.

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30. A method for labeling, comprising placing the label according to claim 1 into a mold, placing a moldable resin in said mold in contact with said label, and molding or forming said moldable resin into an article comprising said label.

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